



Schedule of Scope to Certificate of Approval Approved Component - Capability Approval

IECQ Certificate No.: C-IECQ BSI 13.0003

CB Certificate No.: E091/CA

Schedule Number: IECQ-C BSI 13.0003-S Rev No.: 3 Revision Date: 2016/11/24 Page 1 of 1

Manufacturer: Merlin Flex Ltd

Place of Manufacture: Prospect Way, Hartlepool

Test Reports:	Issue:	Date:
002	1	October 1996
CA Test Report 001	1	October 2010

Board Types: Flexible without through connections: BS CECC 123 400-003
Flexible single-sided and double-sided with through connections: BS CECC 123 500-003

Base Materials: Polyimide Film Base Stiffener
Epoxy Woven Glass Rigidiser

Board Size: 270 mm x 410 mm Maximum

Conductors: Minimum Width: 0.1 mm ± 0.05 mm
Minimum Spacing: 0.1 mm ± 0.5 mm

Plated Through Hole diameters: 0.42 mm Minimum (finished); for component lead insertion
0.25 mm mounting Minimum (drilled); via hole

Finishes: *Bare Copper
*Hot Air Solder Levelling
Adhesive coated film coverlayer
Liquid Photopolymer Solder Mask

* These finishes meet the solderability requirements of IEC 60326-2.